



MiniSKiiP® CON 1

1600 V / 35 A

Features

- Single phase rectifier
- Brake circuit
- Integrated PTC
- Solder-free spring contact technology

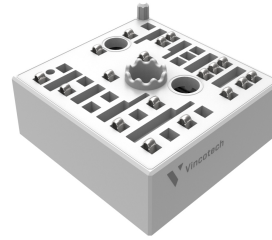
Target applications

- Embedded Drives
- Industrial Drives

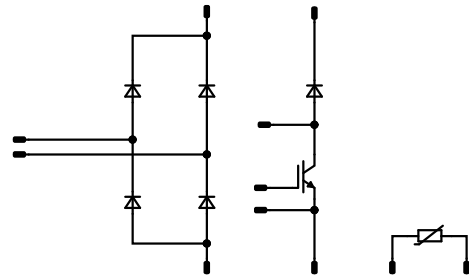
Types

- 80-M1164KA035RW01-K537I10

MiniSKiiP® 1 16 mm housing



Schematic





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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Brake Switch				
Collector-emitter voltage	V_{CES}		650	V
Collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	52	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	92	W
Gate-emitter voltage	V_{GES}		± 30	V
Maximum junction temperature	T_{jmax}		175	°C

Brake Diode

Peak repetitive reverse voltage	V_{RRM}		650	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	49	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	74	W
Maximum junction temperature	T_{jmax}		175	°C

Rectifier Diode

Peak repetitive reverse voltage	V_{RRM}		1600	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	40	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	270	A
Surge current capability	I^2t		370	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	66	W
Maximum junction temperature	T_{jmax}		150	°C



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80-M1164KA035RW01-K537I10
datasheet

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
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Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+(T_{jmax} - 25)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	5500	V
Creepage distance		With std lid For more informations see handling instructions	6,3	mm
Clearance		With std lid For more informations see handling instructions	6,3	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$		5	0,033	25	5	6	7	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	15		50	25 125 150		1,5 1,66 1,7	1,9 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}	0	650		25			0,01	mA
Gate-emitter leakage current	I_{GES}	30	0		25			0,2	µA
Internal gate resistance	r_g						None		Ω
Input capacitance	C_{ies}						4200		pF
Output capacitance	C_{oes}	$f = 1 \text{ Mhz}$	0	30	25		104		pF
Reverse transfer capacitance	C_{res}						79		pF
Gate charge	Q_g	15	400	50	25		141		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 2,5 \text{ W/mK}$ (HPTP)					1,03		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 8 \Omega$ $R_{goff} = 8 \Omega$	0/15	400	50	25		62,4		ns				
						125		55,8						
						150		51,2						
Rise time	t_r									25		22,4		ns
										125		24,6		
										150		25,4		
Turn-off delay time	$t_{d(off)}$									25		185,8		ns
						125		211,2						
						150		216,6						
Fall time	t_f					25		13,6		ns				
						125		18,57						
						150		19,23						
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 1,7 \mu\text{C}$ $Q_{tFWD} = 2,72 \mu\text{C}$ $Q_{tFWD} = 3,14 \mu\text{C}$				25		0,91		mWs				
						125		1,12						
						150		1,19						
Turn-off energy (per pulse)	E_{off}					25		0,726		mWs				
						125		0,965						
						150		1,04						



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datasheet

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		
Brake Diode										
Static										
Forward voltage	V_F			50	25 125 150		1,5 1,57 1,54	1,9 ⁽¹⁾		V
Reverse leakage current	I_R	$V_T = 650$ V			25			10		μA
Thermal										
Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 2,5$ W/mK (HPTP)					1,28			K/W
Dynamic										
Peak recovery current	I_{RRM}				25 125 150		51,29 58,76 61,56			A
Reverse recovery time	t_{rr}				25 125 150		66,29 105,04 115,65			ns
Recovered charge	Q_r	$di/dt=2596$ A/μs $di/dt=2820$ A/μs $di/dt=2555$ A/μs	0/15	400	50	25 125 150	1,7 2,72 3,14			μC
Reverse recovered energy	E_{rec}				25 125 150		0,372 0,678 0,799			mWs
Peak rate of fall of recovery current	$(di_r/dt)_{max}$				25 125 150		1556 1448 1485			A/μs



Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	V_{CE} [V]	T_j [°C]	Min	Typ	Max	

Rectifier Diode

Static

Forward voltage	V_F				28	25 125		1,15 1,1		V
Reverse leakage current	I_R	$V_i = 1600$ V				25 150			100 1000	μ A

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 2,5$ W/mK (HPTP)						1,06		K/W
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Thermistor

Static

Rated resistance	R					25		1		k Ω
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1670$ Ω				100	-2		2	%
Maximum Current	I_{max}							3		mA
Power dissipation constant	d					25		0,76		mW/K
A-value	A							$7,635 \times 10^{-3}$		1/K
B-value	B							$1,73 \times 10^{-5}$		1/K ²
Vincotech Thermistor Reference									E	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.

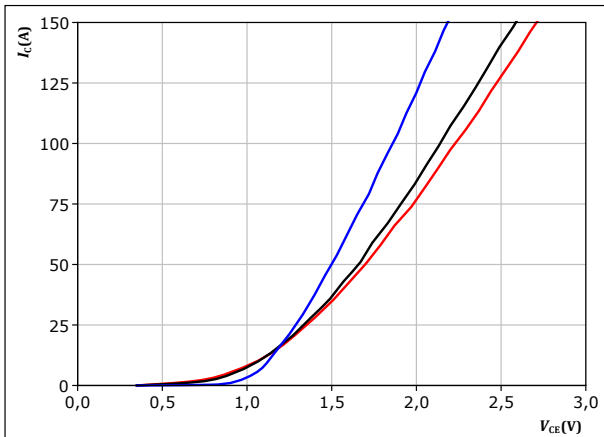


Brake Switch Characteristics

figure 1. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

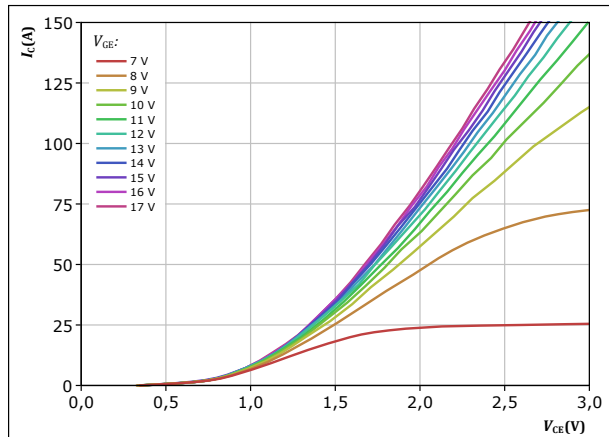


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 2. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

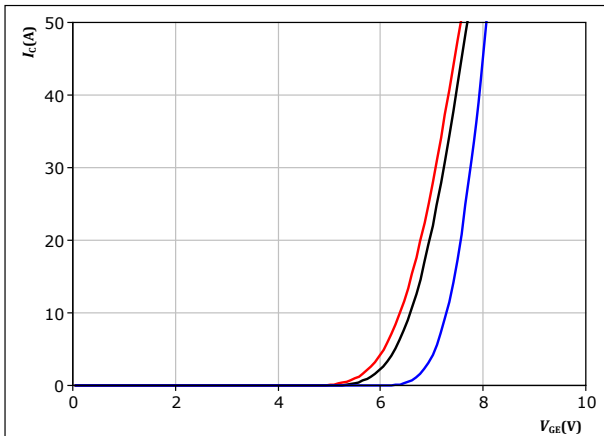


$t_p = 250 \mu s$
 $T_j = 150 \text{ °C}$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

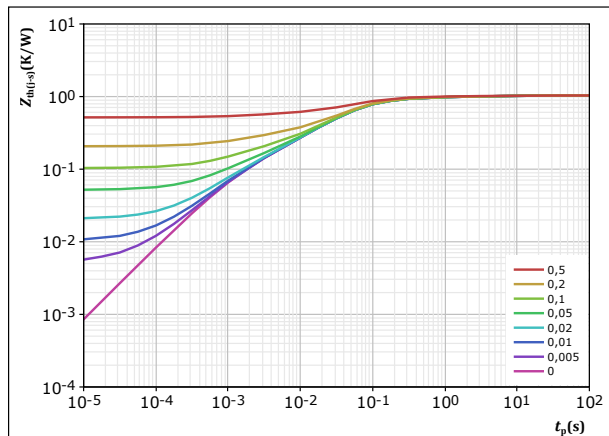


$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 4. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,035 \text{ K/W}$

IGBT thermal model values

R (K/W)	τ (s)
3,85E-02	8,76E+00
7,22E-02	7,46E-01
1,92E-01	1,33E-01
5,55E-01	4,45E-02
1,03E-01	8,66E-03
6,94E-02	1,33E-03
4,78E-03	6,42E-04

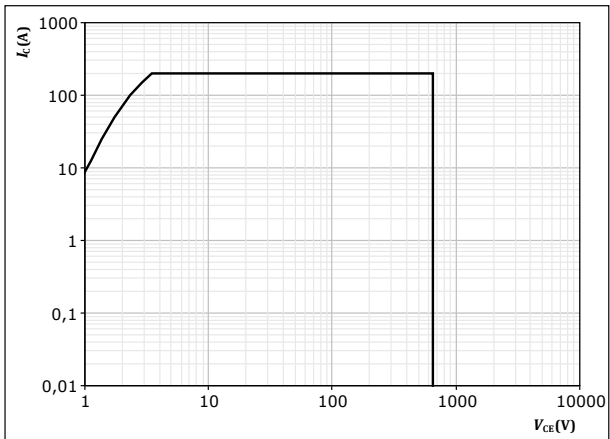


Brake Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



D = single pulse
T_s = 80 °C
V_{CE} = 15 V
T_j = T_{jmax}



Brake Diode Characteristics

figure 6. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

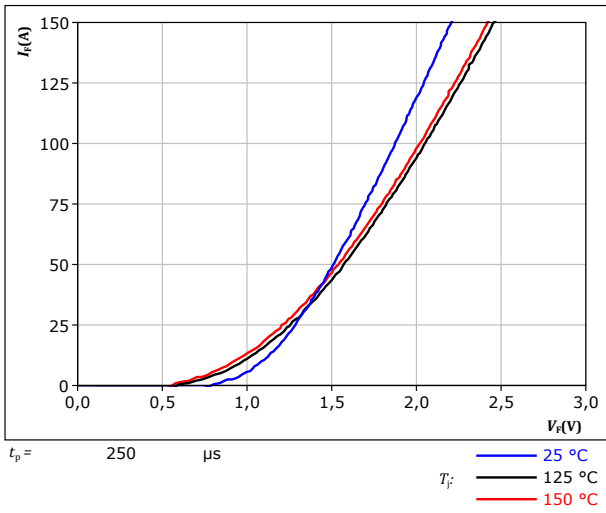
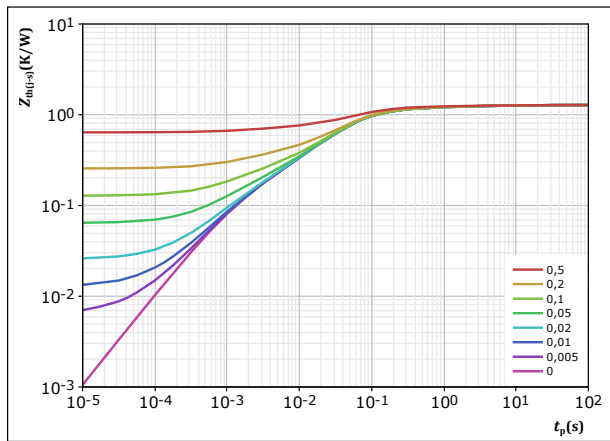


figure 7. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 1,279 \text{ K/W}$
 FWD thermal model values

R (K/W)	τ (s)
4,76E-02	8,76E+00
8,93E-02	7,46E-01
2,37E-01	1,33E-01
6,86E-01	4,45E-02
1,28E-01	8,66E-03
8,58E-02	1,33E-03
5,91E-03	6,42E-04



Rectifier Diode Characteristics

figure 8. Rectifier

Typical forward characteristics

$$I_F = f(V_F)$$

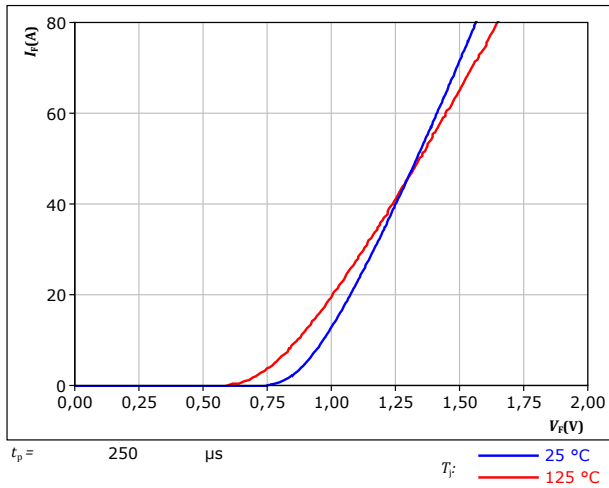
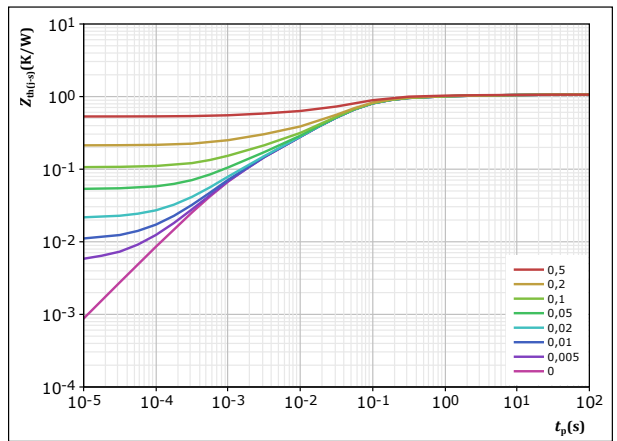


figure 9. Rectifier

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$

$R_{th(j-s)} = 1,064 \text{ K/W}$

Rectifier thermal model values

$R \text{ (K/W)}$	$\tau \text{ (s)}$
3,96E-02	8,76E+00
7,42E-02	7,46E-01
1,97E-01	1,33E-01
5,70E-01	4,45E-02
1,06E-01	8,66E-03
7,14E-02	1,33E-03
4,92E-03	6,42E-04

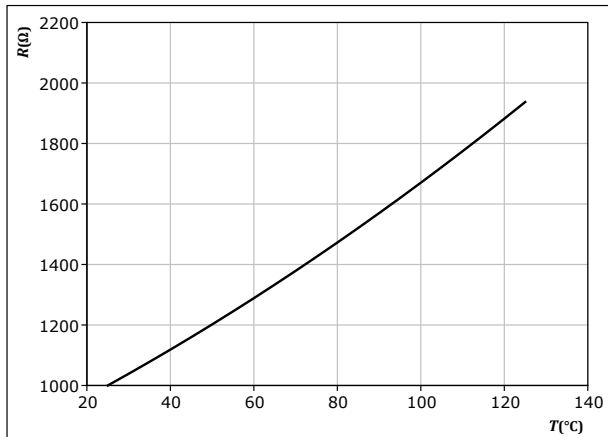


Thermistor Characteristics

figure 10. Thermistor

Typical PTC characteristic as function of temperature

$$R_T = f(T)$$



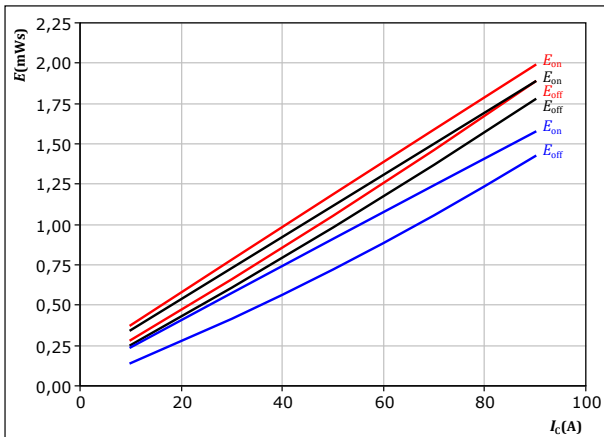


Brake Switching Characteristics

figure 11. IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_c)$$



With an inductive load at

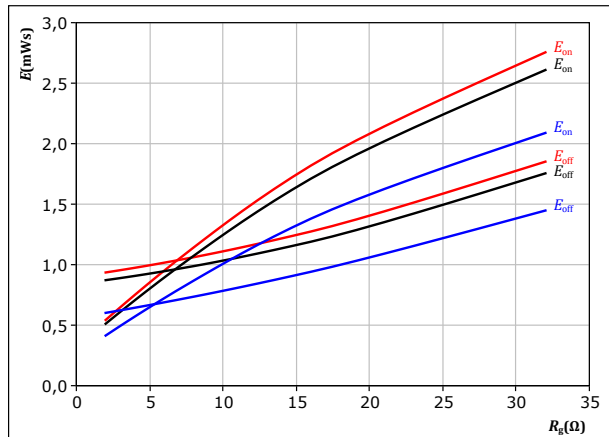
$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 12. IGBT

Typical switching energy losses as a function of gate resistor

$$E = f(R_g)$$



With an inductive load at

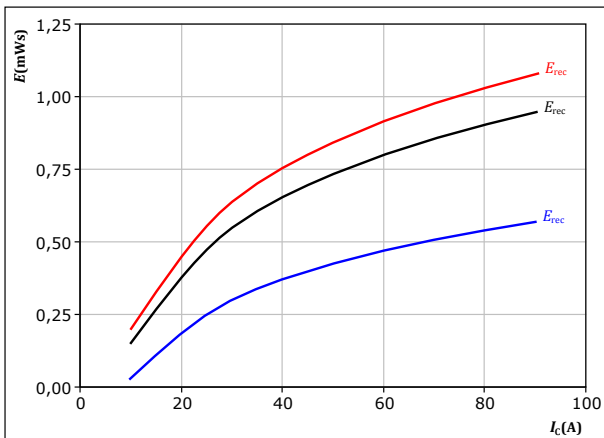
$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $I_c = 50$ A

T_j : — 25 °C
— 125 °C
— 150 °C

figure 13. FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_c)$$



With an inductive load at

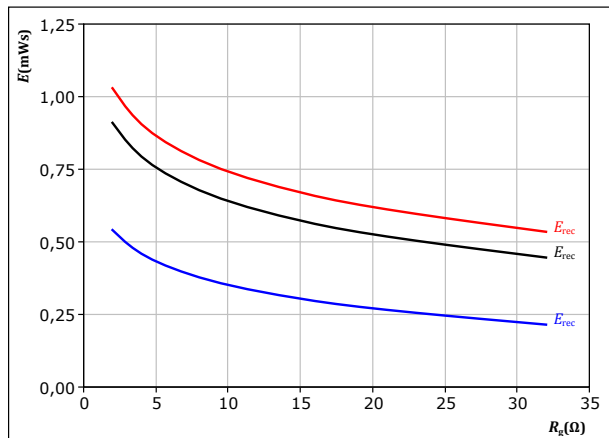
$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 8$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 14. FWD

Typical reverse recovered energy loss as a function of gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $I_c = 50$ A

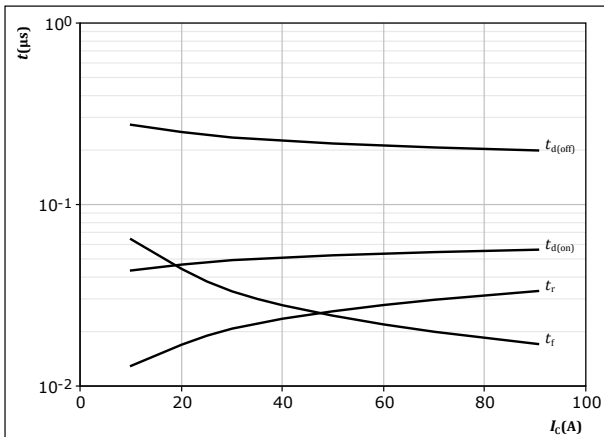
T_j : — 25 °C
— 125 °C
— 150 °C



Brake Switching Characteristics

figure 15. IGBT

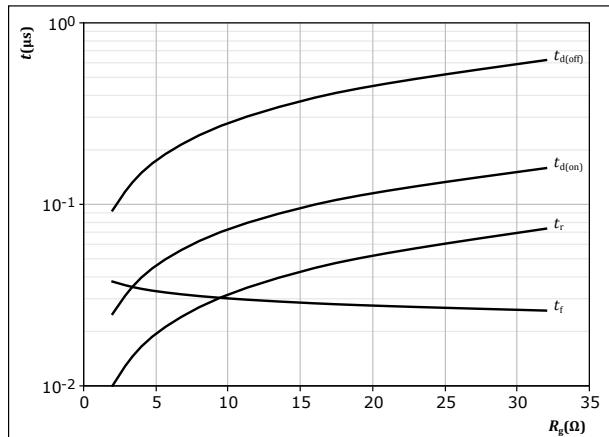
Typical switching times as a function of collector current
 $t = f(I_c)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

figure 16. IGBT

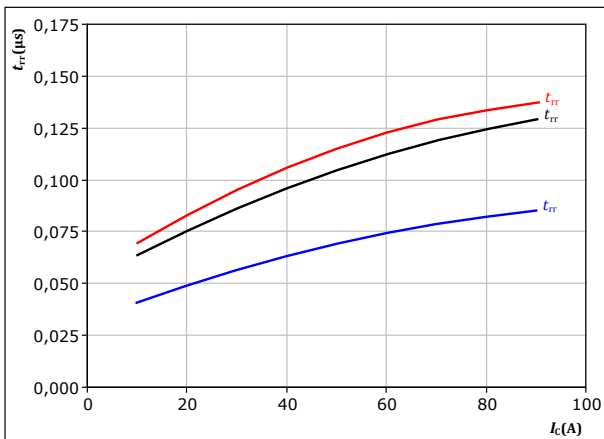
Typical switching times as a function of gate resistor
 $t = f(R_g)$



With an inductive load at
 $T_j = 150 \text{ }^\circ\text{C}$
 $V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 50 \text{ A}$

figure 17. FWD

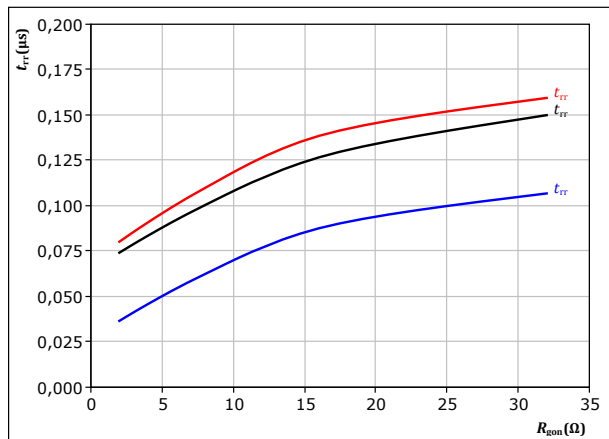
Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at
 $V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$
 $T_j:$ — 25 °C
 — 125 °C
 — 150 °C

figure 18. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at
 $V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 50 \text{ A}$
 $T_j:$ — 25 °C
 — 125 °C
 — 150 °C

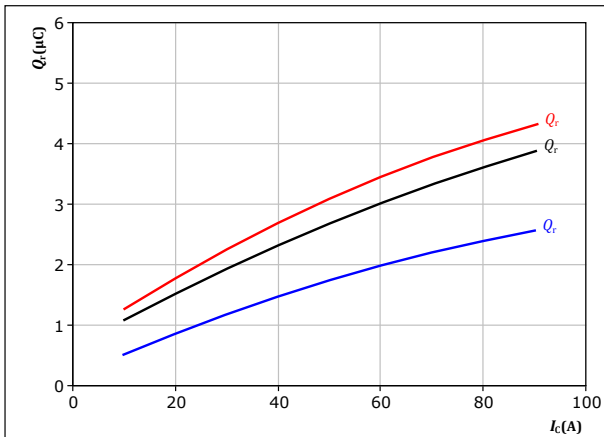


Brake Switching Characteristics

figure 19. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

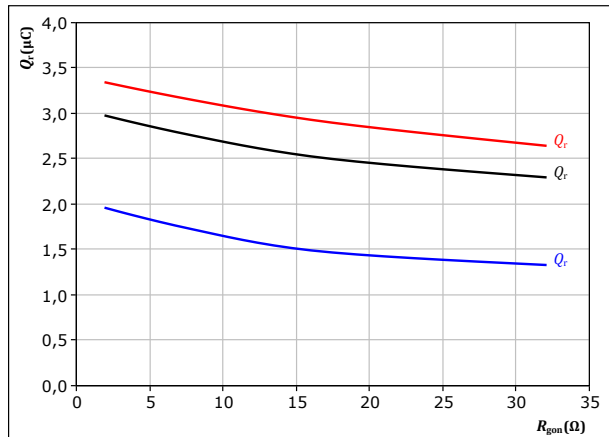
$V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 20. FWD

Typical recovered charge as a function of turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

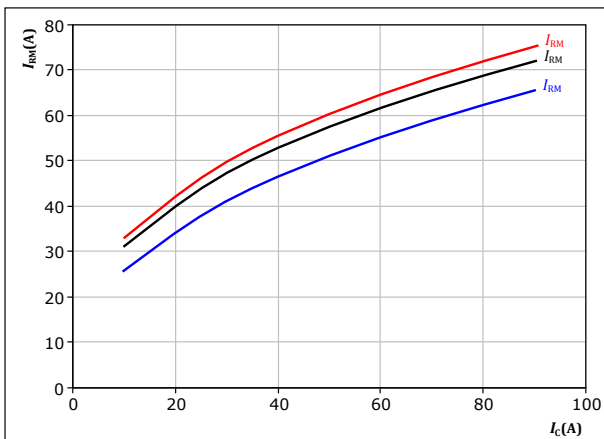
$V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 50 \text{ A}$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 21. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

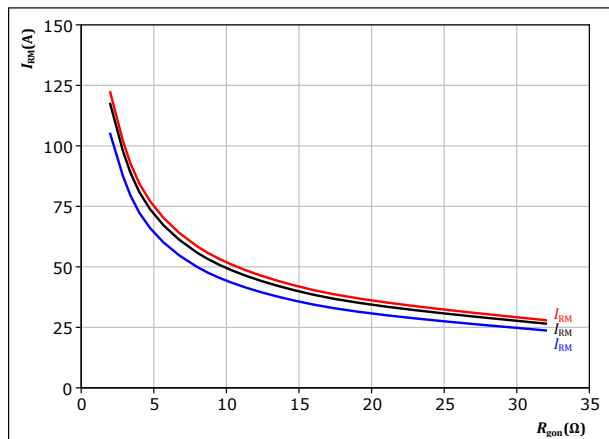
$V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$

T_j : — 25 °C
— 125 °C
— 150 °C

figure 22. FWD

Typical peak reverse recovery current as a function of turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 400 \text{ V}$
 $V_{GE} = 0/15 \text{ V}$
 $I_c = 50 \text{ A}$

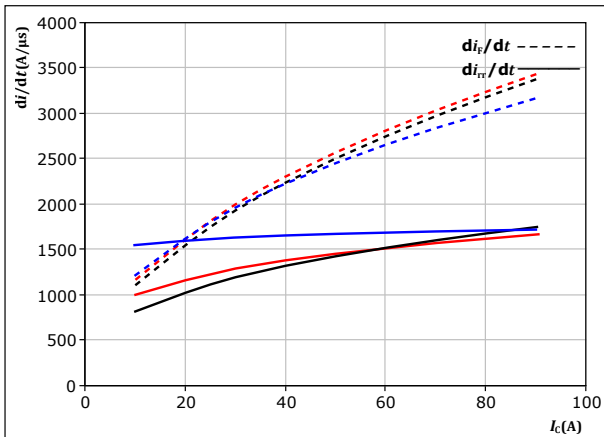
T_j : — 25 °C
— 125 °C
— 150 °C



Brake Switching Characteristics

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



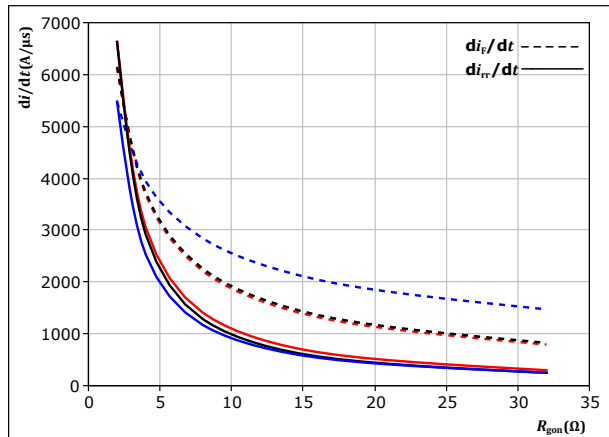
With an inductive load at

$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $R_{gon} = 8$ Ω

T_j : 25 °C
 125 °C
 150 °C

figure 24. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



With an inductive load at

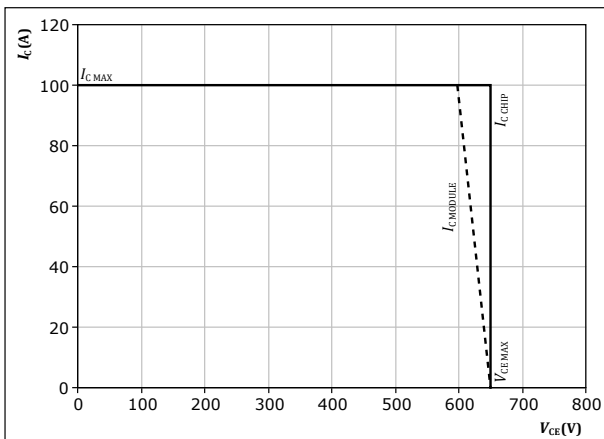
$V_{CE} = 400$ V
 $V_{GE} = 0/15$ V
 $I_C = 50$ A

T_j : 25 °C
 125 °C
 150 °C

figure 25. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150$ °C
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω



Brake Switching Definitions

figure 26. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

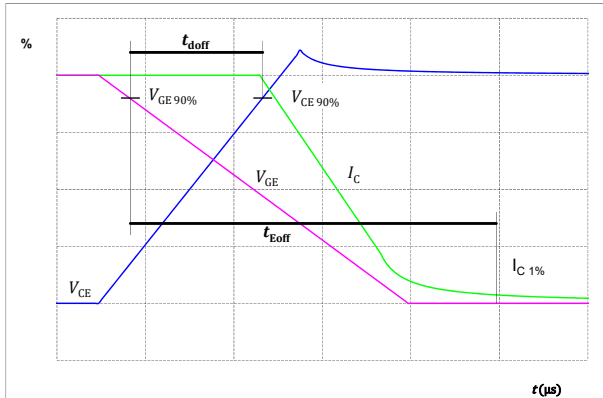


figure 27. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

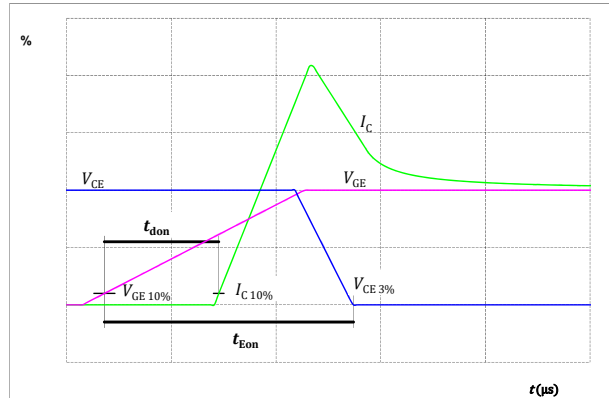


figure 28. IGBT

Turn-off Switching Waveforms & definition of t_f

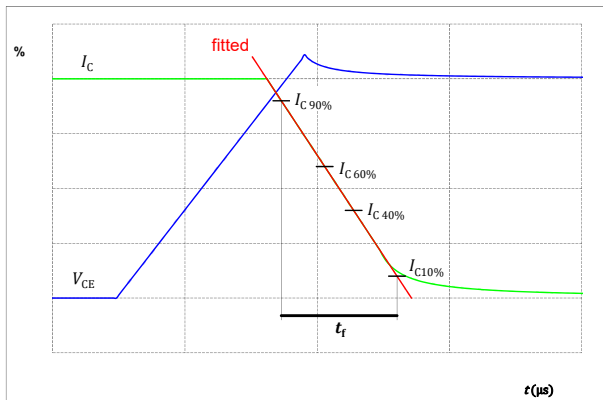
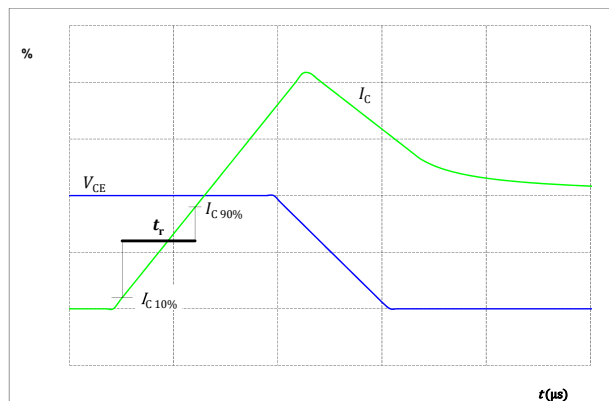


figure 29. IGBT

Turn-on Switching Waveforms & definition of t_r





Brake Switching Definitions

figure 30. FWD

Turn-off Switching Waveforms & definition of t_{rr}

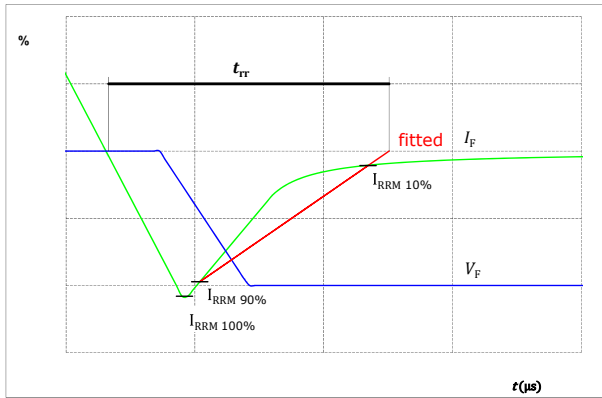
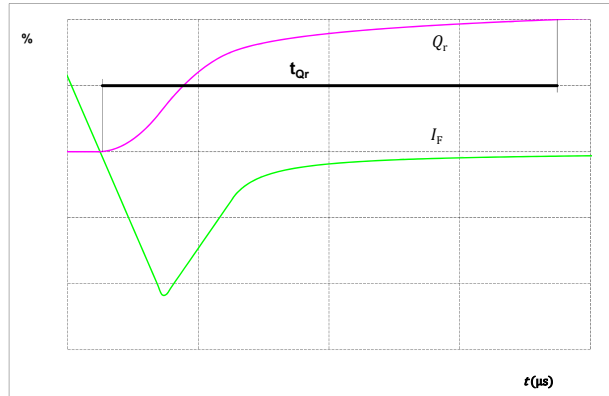


figure 31. FWD


Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



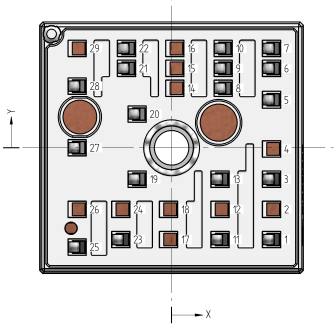


Vincotech

Ordering Code	
Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	80-M1164KA035RW01-K537I10-/0A/
With thin lid (2.8mm height) + no thermal grease	80-M1164KA035RW01-K537I10-/0B/
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M1164KA035RW01-K537I10-/1A/
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M1164KA035RW01-K537I10-/1B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M1164KA035RW01-K537I10-/4A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M1164KA035RW01-K537I10-/4B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M1164KA035RW01-K537I10-/5A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M1164KA035RW01-K537I10-/5B/

Marking						
Text	Name		Date code	UL & VIN	Lot	Serial
		NN-NNNNNNNNNNNNNNNN- TTTTTTTVV		WWYY	UL VIN	LLLLL
Datamatrix		Type&Ver	Lot number	Serial	Date code	
	TTTTTTTVV	LLLLL	SSSS	WWYY		

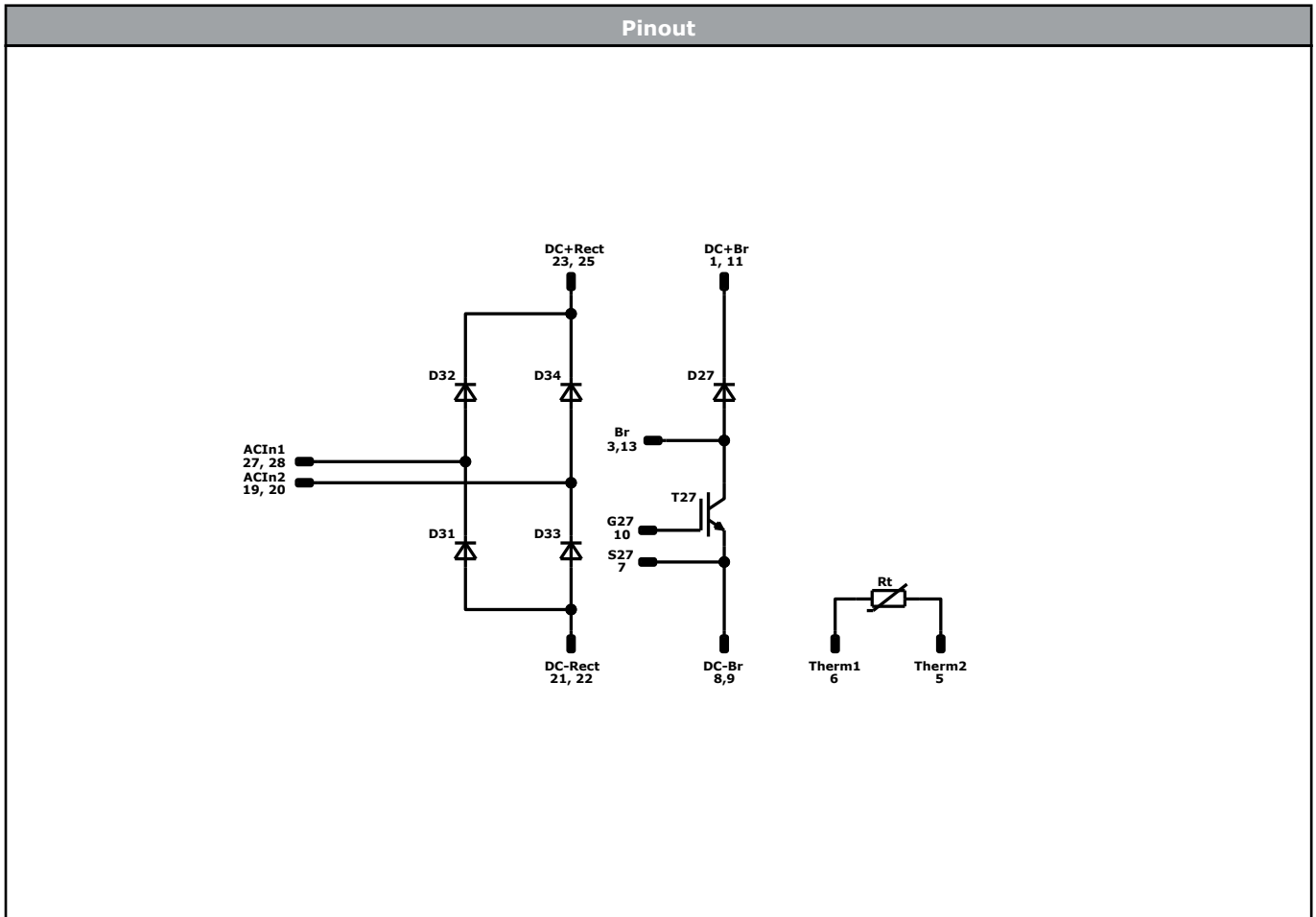
Outline				
Pin table [mm]				
Pin	X	Y	Function	
1	15,93	-14,6	DC+Br	
2	not assembled			
3	15,93	-5	Br	
4	not assembled			
5	15,93	7,62	Therm2	
6	15,93	12,62	Therm1	
7	15,93	15,8	S27	
8	8,23	9,45	DC-Br	
9	8,23	12,62	DC-Br	
10	8,23	15,8	G27	
11	7,73	-14,6	DC+Br	
12	not assembled			
13	7,73	-5	Br	
14	not assembled			
15	not assembled			
16	not assembled			
17	not assembled			
18	not assembled			
19	-5,47	-5	ACIn2	
20	-5,47	5,35	ACIn2	
21	-7,17	12,62	DC-Rect	
22	-7,17	15,8	DC-Rect	
23	-8,07	-14,6	DC+Rect	
24	not assembled			
25	-15,02	-15,8	DC+Rect	
26	not assembled			
27	-15,02	0	ACIn1	
28	-15,02	9,8	ACIn1	
29	not assembled			



Pad positions refers to center point. For more informations on pad design please see package data



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Identification					
ID	Component	Voltage	Current	Function	Comment
T1	IGBT	650 V	50 A	Brake Switch	
D5	FWD	650 V	50 A	Brake Diode	
D2, D1, D4, D3	Rectifier	1600 V	40 A	Rectifier Diode	
PTC	Thermistor			Thermistor	




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Packaging instruction				
Standard packaging quantity (SPQ) 120	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for MiniSKiiP® 1 packages see vincotech.com website.

Package data
Package data for MiniSKiiP® 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
80-M1164KA035RW01-K537I10-D1-14	24 Jul. 2020		

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.